

LUXBEAM® BEAM30

Thick copper and power modules at 30 μm

The high-power end of the lineup: a 1–7 channel 4-peak LED photohead for thick-copper PCB, SiC and GaN power modules, high-current substrates and solder mask, on the largest panels.

Full specification

IMAGING & LAYOUT	
Resolution	30 μm (high power)
Light source	1–7 channel 4-peak LED
Throughput — 515 × 510 mm panel	~9.5 s/side
Typical applications	Thick-copper PCB, SiC / GaN power modules, high-current substrates, solder mask
Substrate / panel	Largest panels, high power
Segment	High power

Figures are for discussion and to be confirmed per application. Throughput depends on resist and energy density — send us both and a field application engineer will verify them for your process.